

Technical Data Sheet

Ultra Micronized Dicyandiamide
CAS No. 461-58-5

DESCRIPTION

Ultra micronized Dicyandiamide is a curing agent containing 1.5% of an inert flow control additive to inhibit clumping and improve handling. It is designed for use as a latent curing agent for epoxy resins.

ADVANTAGES

- Fine particle size provides enhanced reactivity versus coarser grades
- Easily dispersed in liquid resins
- Shelf stability up to 6 months at 25 in properly formulated systems
- Activation temperature can be easily varied from 180 to 95 with appropriate accelerator selection

STORAGE LIFE

At least 12 months from the date of manufacture in the original sealed container at ambient temperature. Store away from excessive heat and humidity in tightly closed containers.

HEALTH & SAFETY PRECAUTIONS

Ultra Micronized Dicyandiamide is not flammable, corrosive or explosive. Dicyandiamide will decompose slowly above 80°C in water to generate ammonia, so material should be kept dry and away from steam pipes or excessively hot areas. While Ultra Micronized Dicyandiamide is not a primary skin or eye irritant, epoxy resins in which it is used can produce irritation. Removal with soap and water is sufficient. Avoid using solvents as these can dry the skin and increase the irritation potential of epoxy resins.

APPLICATIONS

- One Component Adhesives
- Epoxy Powder Coatings
- Prepregs and Film Adhesives
- Electronic Potting and Encapsulating Compounds

TY PICAL PROPERTIES

Appearance	free flowing white powder
Melt Point (°C)	209-212
Purity (%)	>98
Free Water (%)	<0.3
Particle Size (98%) [μm]	<10
Heat Distortion Temperature (°C)	125